

New Project Proposal: Pluggable Multi-Purpose Module (PMM)

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New Project Proposal: Pluggable Multi-Purpose Module (PMM)

- Goal is to define the mechanicals of a module form factor with the connector on the narrow side. Form factor defined to support applications that require higher power and a larger volumetric. Basic tenants:
 - Bigger than E3
 - Needs to support up to ~400W
 - Needs to support xPUs with DIMMs oriented vertically and network connectors on front (e.g., QSFP)
 - Needs to support SFF-TA-1002/SFF-TA-1020 variant (up to 32 diff pairs + advanced NIC sidebands)
 - Leverages elements of 1009 (e.g., pinout, electricals).
 - Ability to plug a 1009 device into the connector (e.g., E3 NVMe device into an PMM host).
- Editor: Anant Thakar, Anthony Constantine
- Sponsors:
 - 1. Cisco Systems
 - 2. HPE
 - 3. Intel



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- IP Declaration (if applicable):
 - N/A
- Request for an Ad Hoc meeting
 - Will need some sort of consistent group discussion so request a separate meeting time/bridge until this project is ready for approval ballot.



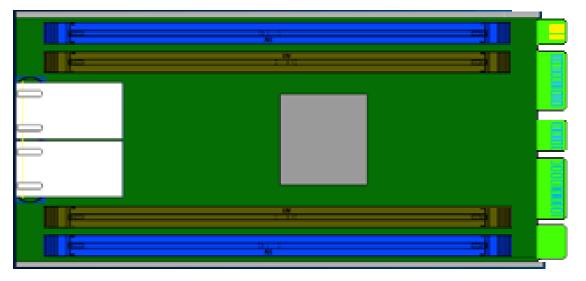
Backup

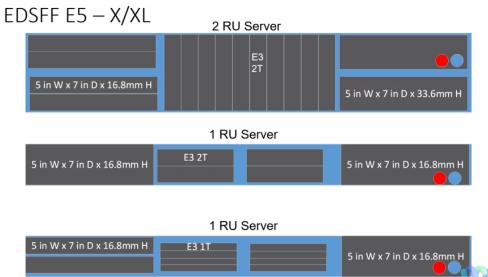


What is PMM?

Working LZ:

- SFF-TA-1002 like (32 lanes, NIC sidebands, extra power)
- Power support up to ~400W
- Thickness: can fit in 1U horizontal
- Length: DIMMs + other components driven
- Width: xPU + DIMMs driven







Use cases

- 1. sNIC/DPU compute/Accelerators
- 2. High TDP GPU's 300W+
- 3. Memory Cassette (Large memory pool)
- 4. Modular Edge compute/Multi Node (CPU +DIMM +Front IO)

